

Part Number: **MBR10100CTP**
Weight (mg): 1309.53

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall	
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	0.20	2.68	1000000	2045	
Leadframe & Clip	KFC Copper Alloy	P	7723-14-0	0.03%	27.92	365.64	300	84	
		Fe	1309-37-1	0.10%			1000	279	
		Cu	7440-50-8	99.87%			998700	278852	
Die Attach Pad Platin	Nickel	Ni	7440-02-0	100.00%	0.04	0.58	1000000	440	
Heatsink	6063 Alloy	Si	7440-21-3	0.40%	32.99	432.05	4000	1320	
		Fe	1309-37-1	0.35%			3500	1155	
		Cu	7440-50-8	0.10%			1000	330	
		Mn	7439-96-5	0.10%			1000	330	
		Mg	7439-95-4	0.70%			7000	2310	
		Cr (Not CrVI)	7440-47-3	0.10%			1000	330	
		Zn	7440-66-6	0.10%			1000	330	
		Ti	7440-32-6	0.10%			1000	330	
		Al	7429-90-5	98.05%			980500	323497	
Bonding Wire	Aluminum Wire	AL	7429-90-5	100.00%	0.31	4.00	1000000	3054	
Encapsulation	CEL-3650	Silica	14808-60-7	79.80%	37.82	495.27	798000	301807	
		Epoxy Resin	-----	11.00%			110000	41602	
		Phenol Resin	-----	5.00%			50000	18910	
		Brominated Epoxy Resin	40039-93-8	3.00%			30000	11346	
		Sb2O3	1309-64-4	1.00%			10000	3782	
Carbon black	1309-64-4	0.20%	2000	756					
Solder Paste	RoHS Exempt High Temperature	Pb	7439-92-1	92.50%	0.18	2.36	925000	1668	
		Sn	7440-31-5	5.00%			50000	90	
		Ag	7440-22-4	2.50%			25000	45	
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	0.53	6.95	1000000	5308	
					Total	100.00	1309.53		1000000

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not

* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold. These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, Material Composition Declaration for Electronic Products.

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

- | | |
|--|--|
| Asbestos | Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.) |
| Azo compounds | Ozone Depleting Substances - Class II (HCFCs) |
| Cadmium and cadmium compounds | Perfluorooctane Sulphonate (PFOS) or related compounds |
| Certain Shortchain Chlorinated Paraffins | Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE |
| Chlorinated organic compounds | Polychlorinated Biphenyls (PCBs) |
| Hexavalent chromium compounds | Polychlorinated Naphthalenes (> 3 chlorine atoms) |
| Lead and lead compounds | Radioactive Substances |
| Mercury and mercury compounds | Tributyl Tin (TBT) and Triphenyl Tin (TPT) |
| Organic tin compounds | Tributyl Tin Oxide (TBTO) |

RoHS Exemption 7a for Pb in High Temperature, High %Pb in Solder is applied

Part Number: **MBR10150CTP**
Weight (mg): 1310.33

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	0.28	3.70	1000000	2822
Leadframe & Clip	KFC Copper Alloy	P	7723-14-0	0.03%	27.90	365.64	300	84
		Fe	1309-37-1	0.10%			1000	279
		Cu	7440-50-8	99.87%			998700	278680
Die Attach Pad Platin	Nickel	Ni	7440-02-0	100.00%	0.04	0.58	1000000	439
Heatsink	6063 Alloy	Si	7440-21-3	0.40%	32.97	432.05	4000	1319
		Fe	1309-37-1	0.35%			3500	1154
		Cu	7440-50-8	0.10%			1000	330
		Mn	7439-96-5	0.10%			1000	330
		Mg	7439-95-4	0.70%			7000	2308
		Cr (Not CrVI)	7440-47-3	0.10%			1000	330
		Zn	7440-66-6	0.10%			1000	330
		Ti	7440-32-6	0.10%			1000	330
		Al	7429-90-5	98.05%			980500	323298
Bonding Wire	Aluminum Wire	AL	7429-90-5	100.00%	0.31	4.00	1000000	3052
Encapsulation	CEL-3650	Silica	14808-60-7	79.80%	37.71	494.16	798000	300946
		Epoxy Resin		11.00%			110000	41484
		Phenol Resin		5.00%			50000	18856
		Brominated Epoxy Resin	40039-93-8	3.00%			30000	11314
		Sb2O3	1309-64-4	1.00%			10000	3771
		Carbon black	1309-64-4	0.20%			2000	754
Solder Paste	RoHS Exempt High Temperature	Pb	7439-92-1	92.50%	0.25	3.26	925000	2299
		Sn	7440-31-5	5.00%			50000	124
		Ag	7440-22-4	2.50%			25000	62
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	0.53	6.95	1000000	5305
				Total	100.00	1310.33		1000000

Tolerance ±10%

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- | | |
|--|---|
| Asbestos | Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.) |
| Azo compounds | Ozone Depleting Substances - Class II (HCFCs) |
| Cadmium and cadmium compounds | Perfluorooctane Sulphonate (PFOS) or related compounds |
| Certain Shortchain Chlorinated Paraffins | Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including Deca BDE |
| Chlorinated organic compounds | Polychlorinated Biphenyls (PCBs) |
| Hexavalent chromium compounds | Polychlorinated Naphthalenes (> 3 chlorine atoms) |
| Lead and lead compounds | Radioactive Substances |
| Mercury and mercury compounds | Tributyl Tin (TBT) and Triphenyl Tin (TPT) |
| Organic tin compounds | Tributyl Tin Oxide (TBTO) |

RoHS Exemption 7a for Pb in High Temperature, High %Pb in Solder is applied

Part Number: **MBR20100CTP**
Weight (mg): 1311.83

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	0.43	5.59	1000000	4263
Leadframe & Clip	KFC Copper Alloy	P	7723-14-0	0.03%	27.87	365.64	300	84
		Fe	1309-37-1	0.10%			1000	279
		Cu	7440-50-8	99.87%			998700	278363
Die Attach Pad Platin	Nickel	Ni	7440-02-0	100.00%	0.04	0.58	1000000	439
Heatsink	6063 Alloy	Si	7440-21-3	0.40%	32.94	432.05	4000	1317
		Fe	1309-37-1	0.35%			3500	1153
		Cu	7440-50-8	0.10%			1000	329
		Mn	7439-96-5	0.10%			1000	329
		Mg	7439-95-4	0.70%			7000	2305
		Cr (Not CrVI)	7440-47-3	0.10%			1000	329
		Zn	7440-66-6	0.10%			1000	329
		Ti	7440-32-6	0.10%			1000	329
		Al	7429-90-5	98.05%			980500	322930
Bonding Wire	Aluminum Wire	AL	7429-90-5	100.00%	0.30	4.00	1000000	3049
Encapsulation	CEL-3650	Silica	14808-60-7	79.80%	37.51	492.09	798000	299347
		Epoxy Resin	-----	11.00%			110000	41263
		Phenol Resin	-----	5.00%			50000	18756
		Brominated Epoxy Resin	40039-93-8	3.00%			30000	11254
		Sb2O3	1309-64-4	1.00%			10000	3751
		Carbon black	1309-64-4	0.20%			2000	750
Solder Paste	RoHS Exempt High Temperature	Pb	7439-92-1	92.50%	0.38	4.92	925000	3470
		Sn	7440-31-5	5.00%			50000	188
		Ag	7440-22-4	2.50%			25000	94
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	0.53	6.95	1000000	5299
				Total	100.00	1311.83		1000000

Tolerance ±10%

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This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

- | | |
|--|---|
| Asbestos | Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.) |
| Azo compounds | Ozone Depleting Substances - Class II (HCFCs) |
| Cadmium and cadmium compounds | Perfluorooctane Sulphonate (PFOS) or related compounds |
| Certain Shortchain Chlorinated Paraffins | Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including Deca BDE |
| Chlorinated organic compounds | Polychlorinated Biphenyls (PCBs) |
| Hexavalent chromium compounds | Polychlorinated Naphthalenes (> 3 chlorine atoms) |
| Lead and lead compounds | Radioactive Substances |
| Mercury and mercury compounds | Tributyl Tin (TBT) and Triphenyl Tin (TPT) |
| Organic tin compounds | Tributyl Tin Oxide (TBTO) |

RoHS Exemption 7a for Pb in High Temperature, High %Pb in Solder is applied

Part Number: **MBR20150CTP**
Weight (mg): 1313.35

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	0.57	7.52	1000000	5726
Leadframe & Clip	KFC Copper Alloy	P	7723-14-0	0.03%	27.84	365.64	300	84
		Fe	1309-37-1	0.10%			1000	278
		Cu	7440-50-8	99.87%			998700	278041
Die Attach Pad Platin	Nickel	Ni	7440-02-0	100.00%	0.04	0.58	1000000	438
Heatsink	6063 Alloy	Si	7440-21-3	0.40%	32.90	432.05	4000	1316
		Fe	1309-37-1	0.35%			3500	1151
		Cu	7440-50-8	0.10%			1000	329
		Mn	7439-96-5	0.10%			1000	329
		Mg	7439-95-4	0.70%			7000	2303
		Cr (Not CrVI)	7440-47-3	0.10%			1000	329
		Zn	7440-66-6	0.10%			1000	329
		Ti	7440-32-6	0.10%			1000	329
		Al	7429-90-5	98.05%			980500	322556
Bonding Wire	Aluminum Wire	AL	7429-90-5	100.00%	0.30	4.00	1000000	3045
Encapsulation	CEL-3650	Silica	14808-60-7	79.80%	37.31	489.99	798000	297723
		Epoxy Resin	-----	11.00%			110000	41040
		Phenol Resin	-----	5.00%			50000	18654
		Brominated Epoxy Resin	40039-93-8	3.00%			30000	11193
		Sb2O3	1309-64-4	1.00%			10000	3731
		Carbon black	1309-64-4	0.20%			2000	746
Solder Paste	RoHS Exempt High Temperature	Pb	7439-92-1	92.50%	0.50	6.61	925000	4658
		Sn	7440-31-5	5.00%			50000	252
		Ag	7440-22-4	2.50%			25000	126
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	0.53	6.95	1000000	5293
				Total	100.00	1313.35		1000000

Tolerance ±10%

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- | | |
|--|---|
| Asbestos | Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.) |
| Azo compounds | Ozone Depleting Substances - Class II (HCFCs) |
| Cadmium and cadmium compounds | Perfluorooctane Sulphonate (PFOS) or related compounds |
| Certain Shortchain Chlorinated Paraffins | Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including Deca BDE |
| Chlorinated organic compounds | Polychlorinated Biphenyls (PCBs) |
| Hexavalent chromium compounds | Polychlorinated Naphthalenes (> 3 chlorine atoms) |
| Lead and lead compounds | Radioactive Substances |
| Mercury and mercury compounds | Tributyl Tin (TBT) and Triphenyl Tin (TPT) |
| Organic tin compounds | Tributyl Tin Oxide (TBTO) |

RoHS Exemption 7a for Pb in High Temperature, High %Pb in Solder is applied

Part Number: **SBL10x0CTP**
Weight (mg): 1309.65

Part Numbers: SBL1040CTP, SBL1060CTP

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	0.22	2.83	1000000	2158
Leadframe & Clip	KFC Copper Alloy	P	7723-14-0	0.03%	27.92	365.64	300	84
		Fe	1309-37-1	0.10%			1000	279
		Cu	7440-50-8	99.87%			998700	278827
Die Attach Pad Platin	Nickel	Ni	7440-02-0	100.00%	0.04	0.58	1000000	440
Heatsink	6063 Alloy	Si	7440-21-3	0.40%	32.99	432.05	4000	1320
		Fe	1309-37-1	0.35%			3500	1155
		Cu	7440-50-8	0.10%			1000	330
		Mn	7439-95-5	0.10%			1000	330
		Mg	7439-95-4	0.70%			7000	2309
		Cr (Not CrVI)	7440-47-3	0.10%			1000	330
		Zn	7440-66-6	0.10%			1000	330
		Ti	7440-32-6	0.10%			1000	330
		Al	7429-90-5	98.05%			980500	323468
Bonding Wire	Aluminum Wire	AL	7429-90-5	100.00%	0.31	4.00	1000000	3054
Encapsulation	CEL-3650	Silica	14808-60-7	79.80%	37.80	495.11	798000	301682
		Epoxy Resin	-----	11.00%			110000	41585
		Phenol Resin	-----	5.00%			50000	18902
		Brominated Epoxy Resin	40039-93-8	3.00%			30000	11341
		Sb2O3	1309-64-4	1.00%			10000	3780
		Carbon black	1309-64-4	0.20%			2000	756
Solder Paste	RoHS Exempt High Temperature	Pb	7439-92-1	92.50%	0.19	2.49	925000	1760
		Sn	7440-31-5	5.00%			50000	95
		Ag	7440-22-4	2.50%			25000	48
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	0.53	6.95	1000000	5308
				Total	100.00	1309.65		1000000

Tolerance ±10%

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- | | |
|--|---|
| Asbestos | Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.) |
| Azo compounds | Ozone Depleting Substances - Class II (HCFCs) |
| Cadmium and cadmium compounds | Perfluorooctane Sulphonate (PFOS) or related compounds |
| Certain Shortchain Chlorinated Paraffins | Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including Deca DecaBDE |
| Chlorinated organic compounds | Polychlorinated Biphenyls (PCBs) |
| Hexavalent chromium compounds | Polychlorinated Naphthalenes (> 3 chlorine atoms) |
| Lead and lead compounds | Radioactive Substances |
| Mercury and mercury compounds | Tributyl Tin (TBT) and Triphenyl Tin (TPT) |
| Organic tin compounds | Tributyl Tin Oxide (TBTO) |

RoHS Exemption 7a for Pb in High Temperature, High %Pb in Solder is applied

Part Number: **SBL2045CTP**
Weight (mg): 1311.30

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	0.38	4.92	1000000	3751
Leadframe & Clip	KFC Copper Alloy	P	7723-14-0	0.03%	27.88	365.64	300	84
		Fe	1309-37-1	0.10%			1000	279
		Cu	7440-50-8	99.87%			998700	278476
Die Attach Pad Platin	Nickel	Ni	7440-02-0	100.00%	0.04	0.58	1000000	439
Heatsink	6063 Alloy	Si	7440-21-3	0.40%	32.95	432.05	4000	1318
		Fe	1309-37-1	0.35%			3500	1153
		Cu	7440-50-8	0.10%			1000	329
		Mn	7439-96-5	0.10%			1000	329
		Mg	7439-95-4	0.70%			7000	2306
		Cr (Not CrVI)	7440-47-3	0.10%			1000	329
		Zn	7440-66-6	0.10%			1000	329
		Ti	7440-32-6	0.10%			1000	329
		Al	7429-90-5	98.05%			980500	323061
Bonding Wire	Aluminum Wire	AL	7429-90-5	100.00%	0.31	4.00	1000000	3050
Encapsulation	CEL-3650	Silica	14808-60-7	79.80%	37.58	492.83	798000	299915
		Epoxy Resin		11.00%			110000	41342
		Phenol Resin		5.00%			50000	18792
		Brominated Epoxy Resin	40039-93-8	3.00%			30000	11275
		Sb2O3	1309-64-4	1.00%			10000	3758
		Carbon black	1309-64-4	0.20%			2000	752
Solder Paste	RoHS Exempt High Temperature	Pb	7439-92-1	92.50%	0.33	4.33	925000	3054
		Sn	7440-31-5	5.00%			50000	165
		Ag	7440-22-4	2.50%			25000	83
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	0.53	6.95	1000000	5301
				Total	100.00	1311.30		1000000

Tolerance ±10%

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- | | |
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| Azo compounds | Ozone Depleting Substances - Class II (HCFCs) |
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| Certain Shortchain Chlorinated Paraffins | Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE |
| Chlorinated organic compounds | Polychlorinated Biphenyls (PCBs) |
| Hexavalent chromium compounds | Polychlorinated Naphthalenes (> 3 chlorine atoms) |
| Lead and lead compounds | Radioactive Substances |
| Mercury and mercury compounds | Tributyl Tin (TBT) and Triphenyl Tin (TPT) |
| Organic tin compounds | Tributyl Tin Oxide (TBTO) |

RoHS Exemption 7a for Pb in High Temperature, High %Pb in Solder is applied

Part Number: **SBL2060CTP**
Weight (mg): 1311.30

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	0.38	4.92	1000000	3751
Leadframe & Clip	KFC Copper Alloy	P	7723-14-0	0.03%	27.88	365.64	300	84
		Fe	1309-37-1	0.10%			1000	279
		Cu	7440-50-8	99.87%			998700	278476
Die Attach Pad Platin	Nickel	Ni	7440-02-0	100.00%	0.04	0.58	1000000	439
Heatsink	6063 Alloy	Si	7440-21-3	0.40%	32.95	432.05	4000	1318
		Fe	1309-37-1	0.35%			3500	1153
		Cu	7440-50-8	0.10%			1000	329
		Mn	7439-96-5	0.10%			1000	329
		Mg	7439-95-4	0.70%			7000	2306
		Cr (Not CrVI)	7440-47-3	0.10%			1000	329
		Zn	7440-66-6	0.10%			1000	329
		Ti	7440-32-6	0.10%			1000	329
		Al	7429-90-5	98.05%			980500	323061
Bonding Wire	Aluminum Wire	AL	7429-90-5	100.00%	0.31	4.00	1000000	3050
Encapsulation	CEL-3650	Silica	14808-60-7	79.80%	37.58	492.83	798000	299915
		Epoxy Resin	-----	11.00%			110000	41342
		Phenol Resin	-----	5.00%			50000	18792
		Brominated Epoxy Resin	40039-93-8	3.00%			30000	11275
		Sb2O3	1309-64-4	1.00%			10000	3758
		Carbon black	1309-64-4	0.20%			2000	752
Solder Paste	RoHS Exempt High Temperature	Pb	7439-92-1	92.50%	0.33	4.33	925000	3054
		Sn	7440-31-5	5.00%			50000	165
		Ag	7440-22-4	2.50%			25000	83
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	0.53	6.95	1000000	5301
				Total	100.00	1311.30		1000000

Tolerance ±10%

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- | | |
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| Azo compounds | Ozone Depleting Substances - Class II (HCFCs) |
| Cadmium and cadmium compounds | Perfluorooctane Sulphonate (PFOS) or related compounds |
| Certain Shortchain Chlorinated Paraffins | Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE |
| Chlorinated organic compounds | Polychlorinated Biphenyls (PCBs) |
| Hexavalent chromium compounds | Polychlorinated Naphthalenes (> 3 chlorine atoms) |
| Lead and lead compounds | Radioactive Substances |
| Mercury and mercury compounds | Tributyl Tin (TBT) and Triphenyl Tin (TPT) |
| Organic tin compounds | Tributyl Tin Oxide (TBTO) |

RoHS Exemption 7a for Pb in High Temperature, High %Pb in Solder is applied

Part Number: **SBL3040CTP**
Weight (mg): 1312.96

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	0.46	6.01	1000000	4578
Leadframe & Clip	KFC Copper Alloy	P	7723-14-0	0.03%	27.85	365.64	300	84
		Fe	1309-37-1	0.10%			1000	278
		Cu	7440-50-8	99.87%			998700	278123
Die Attach Pad Platin	Nickel	Ni	7440-02-0	100.00%	0.04	0.58	1000000	439
Heatsink	6063 Alloy	Si	7440-21-3	0.40%	32.91	432.05	4000	1316
		Fe	1309-37-1	0.35%			3500	1152
		Cu	7440-50-8	0.10%			1000	329
		Mn	7439-96-5	0.10%			1000	329
		Mg	7439-95-4	0.70%			7000	2303
		Cr (Not CrVI)	7440-47-3	0.10%			1000	329
		Zn	7440-66-6	0.10%			1000	329
		Ti	7440-32-6	0.10%			1000	329
		Al	7429-90-5	98.05%			980500	322652
Bonding Wire	Aluminum Wire	AL	7429-90-5	100.00%	0.61	8.00	1000000	6093
Encapsulation	CEL-3650	Silica	14808-60-7	79.80%	37.20	488.44	798000	296867
		Epoxy Resin		11.00%			110000	40921
		Phenol Resin		5.00%			50000	18601
		Brominated Epoxy Resin	40039-93-8	3.00%			30000	11160
		Sb2O3	1309-64-4	1.00%			10000	3720
		Carbon black	1309-64-4	0.20%			2000	744
Solder Paste	RoHS Exempt High Temperature	Pb	7439-92-1	92.50%	0.40	5.29	925000	3726
		Sn	7440-31-5	5.00%			50000	201
		Ag	7440-22-4	2.50%			25000	101
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	0.53	6.95	1000000	5295
				Total	100.00	1312.96		1000000

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not

* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium,

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

- | | |
|--|---|
| Asbestos | Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.) |
| Azo compounds | Ozone Depleting Substances - Class II (HCFCs) |
| Cadmium and cadmium compounds | Perfluorooctane Sulphonate (PFOS) or related compounds |
| Certain Shortchain Chlorinated Paraffins | Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE |
| Chlorinated organic compounds | Polychlorinated Biphenyls (PCBs) |
| Hexavalent chromium compounds | Polychlorinated Naphthalenes (> 3 chlorine atoms) |
| Lead and lead compounds | Radioactive Substances |
| Mercury and mercury compounds | Tributyl Tin (TBT) and Triphenyl Tin (TPT) |
| Organic tin compounds | Tributyl Tin Oxide (TBTO) |

RoHS Exemption 7a for Pb in High Temperature, High %Pb in Solder is applied

Part Number: **SBL3045CTP**
Weight (mg): 1313.35

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	0.57	7.52	1000000	5726
Leadframe & Clip	KFC Copper Alloy	P	7723-14-0	0.03%	27.84	365.64	300	84
		Fe	1309-37-1	0.10%			1000	278
		Cu	7440-50-8	99.87%			998700	278041
Die Attach Pad Platin	Nickel	Ni	7440-02-0	100.00%	0.04	0.58	1000000	438
Heatsink	6063 Alloy	Si	7440-21-3	0.40%	32.90	432.05	4000	1316
		Fe	1309-37-1	0.35%			3500	1151
		Cu	7440-50-8	0.10%			1000	329
		Mn	7439-96-5	0.10%			1000	329
		Mg	7439-95-4	0.70%			7000	2303
		Cr (Not CrVI)	7440-47-3	0.10%			1000	329
		Zn	7440-66-6	0.10%			1000	329
		Ti	7440-32-6	0.10%			1000	329
		Al	7429-90-5	98.05%			980500	322556
Bonding Wire	Aluminum Wire	AL	7429-90-5	100.00%	0.30	4.00	1000000	3045
Encapsulation	CEL-3650	Silica	14808-60-7	79.80%	37.31	489.99	798000	297723
		Epoxy Resin		11.00%			110000	41040
		Phenol Resin		5.00%			50000	18654
		Brominated Epoxy Resin	40039-93-8	3.00%			30000	11193
		Sb2O3	1309-64-4	1.00%			10000	3731
		Carbon black	1309-64-4	0.20%			2000	746
Solder Paste	RoHS Exempt High Temperature	Pb	7439-92-1	92.50%	0.50	6.61	925000	4658
		Sn	7440-31-5	5.00%			50000	252
		Ag	7440-22-4	2.50%			25000	126
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	0.53	6.95	1000000	5293
				Total	100.00	1313.35		1000000

Tolerance ±10%

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- | | |
|--|---|
| Asbestos | Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.) |
| Azo compounds | Ozone Depleting Substances - Class II (HCFCs) |
| Cadmium and cadmium compounds | Perfluorooctane Sulphonate (PFOS) or related compounds |
| Certain Shortchain Chlorinated Paraffins | Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE |
| Chlorinated organic compounds | Polychlorinated Biphenyls (PCBs) |
| Hexavalent chromium compounds | Polychlorinated Naphthalenes (> 3 chlorine atoms) |
| Lead and lead compounds | Radioactive Substances |
| Mercury and mercury compounds | Tributyl Tin (TBT) and Triphenyl Tin (TPT) |
| Organic tin compounds | Tributyl Tin Oxide (TBTO) |

RoHS Exemption 7a for Pb in High Temperature, High %Pb in Solder is applied

Part Number: **SBL3060CTP**
Weight (mg): 1314.15

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	0.57	7.52	1000000	5723
Leadframe & Clip	KFC Copper Alloy	P	7723-14-0	0.03%	27.82	365.64	300	83
		Fe	1309-37-1	0.10%			1000	278
		Cu	7440-50-8	99.87%			998700	277872
Die Attach Pad Platin	Nickel	Ni	7440-02-0	100.00%	0.04	0.58	1000000	438
Heatsink	6063 Alloy	Si	7440-21-3	0.40%	32.88	432.05	4000	1315
		Fe	1309-37-1	0.35%			3500	1151
		Cu	7440-50-8	0.10%			1000	329
		Mn	7439-96-5	0.10%			1000	329
		Mg	7439-95-4	0.70%			7000	2301
		Cr (Not CrVI)	7440-47-3	0.10%			1000	329
		Zn	7440-66-6	0.10%			1000	329
		Ti	7440-32-6	0.10%			1000	329
		Al	7429-90-5	98.05%			980500	322360
Bonding Wire	Aluminum Wire	AL	7429-90-5	100.00%	0.61	8.00	1000000	6087
Encapsulation	CEL-3650	Silica	14808-60-7	79.80%	37.04	486.79	798000	295599
		Epoxy Resin		11.00%			110000	40747
		Phenol Resin		5.00%			50000	18521
		Brominated Epoxy Resin	40039-93-8	3.00%			30000	11113
		Sb2O3	1309-64-4	1.00%			10000	3704
		Carbon black	1309-64-4	0.20%			2000	741
Solder Paste	RoHS Exempt High Temperature	Pb	7439-92-1	92.50%	0.50	6.61	925000	4656
		Sn	7440-31-5	5.00%			50000	252
		Ag	7440-22-4	2.50%			25000	126
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	0.53	6.95	1000000	5290
				Total	100.00%	1314.15		1000000

Tolerance ±10%

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- | | |
|--|---|
| Asbestos | Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.) |
| Azo compounds | Ozone Depleting Substances - Class II (HCFCs) |
| Cadmium and cadmium compounds | Perfluorooctane Sulphonate (PFOS) or related compounds |
| Certain Shortchain Chlorinated Paraffins | Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE |
| Chlorinated organic compounds | Polychlorinated Biphenyls (PCBs) |
| Hexavalent chromium compounds | Polychlorinated Naphthalenes (> 3 chlorine atoms) |
| Lead and lead compounds | Radioactive Substances |
| Mercury and mercury compounds | Tributyl Tin (TBT) and Triphenyl Tin (TPT) |
| Organic tin compounds | Tributyl Tin Oxide (TBTO) |

RoHS Exemption 7a for Pb in High Temperature, High %Pb in Solder is applied